

# 100V N-Channel Enhancement Mode Power MOSFET

# **Description**

WMO09N10T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

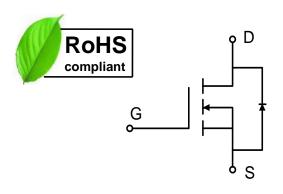
# TO-252

# **Features**

- $V_{DS}$ = 100V,  $I_{D}$  = 9A  $R_{DS(on)}$  < 160m $\Omega$  @  $V_{GS}$  = 10V  $R_{DS(on)}$  < 170m $\Omega$  @  $V_{GS}$  = 4.5V
- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology

# **Applications**

- Power Management Switches
- DC/DC Converter



# **Absolute Maximum Ratings**

Parameter		Symbol	Value	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current@10V <sup>1</sup>	T <sub>C</sub> =25°C	- I <sub>D</sub>	9	A	
	T <sub>C</sub> =100°C		5.7		
	T <sub>A</sub> =25°C		2.3		
	T <sub>A</sub> =70°C		1.8		
Pulsed Drain Current <sup>2</sup>		Іом	18	Α	
Total Power Dissipation <sup>3</sup>	T <sub>C</sub> =25°C	P <sub>D</sub>	2	W	
	T <sub>A</sub> =25°C		31		
Operating Junction and Storage Temperature Range		TJ, TSTG	-55 to+150	°C	

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	R <sub>0JA</sub>	62	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	Rejc	4	°C/W



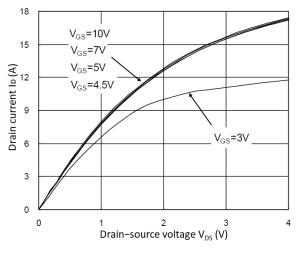
## Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics	'				•		
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V
Gate-body Leakage current		Igss	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
Current	T <sub>J</sub> =25°C	l <sub>DSS</sub>	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V	-	-	10	μА
	T <sub>J</sub> =55°C			-	-	100	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0	1.75	2.5	V
D. 1. 0			$V_{GS} = 10V, I_D = 6A$	-	143	160	
Drain-Source On-Resistance <sup>2</sup>		$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 6A$	-	150	170	mΩ
Forward Transconductance		<b>G</b> fs	$V_{DS} = 5V, I_{D} = 8A$	-	10	-	S
Dynamic Characteristics							
Input Capacitance		C <sub>iss</sub>		-	1077	-	
Output Capacitance  Reverse Transfer Capacitance		$C_{oss}$	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1MHz	-	46	-	pF
		Crss		-	32	-	
<b>Switching Characteristics</b>							
Gate Resistance		$R_g$	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	-	2.2	-	Ω
Total Gate Charge	Total Gate Charge Qg			-	25.5	-	
Gate-Source Charge		$\mathbf{Q}_{gs}$	$V_{GS} = 10V, V_{DS} = 60V, I_{D} = 8A$	-	4.2	-	nC
Gate-Drain Charge		$\mathbf{Q}_{gd}$		-	4.3	-	
Turn-On Delay Time		t <sub>d(on)</sub>		-	17.3	-	
Rise Time Turn-Off Delay Time		t <sub>r</sub>	$V_{GS}$ =10V, $V_{DD}$ =50V, $R_{G}$ = 3.3 $\Omega$ , $I_{D}$ = 1A	-	2.8	-	nS
		t <sub>d(off)</sub>		-	50	-	
Fall Time		tf	]	-	2.8	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.0	V
Continuous Source Current <sup>1,4</sup>		Is	Vg=Vp=0V,Force Current	-	-	9	Α
Body Diode Reverse Recovery Time		t <sub>rr</sub>	1 00 41/44 4000//	-	30	-	nS
Body Diode Reverse Recovery Charge		Qrr	- I <sub>F</sub> = 8A, dl/dt=100A/μs	-	16	-	nC

#### Notes:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.The power dissipation is limited by 150  $^{\circ}\text{C}\,$  junction temperature
- $4 The \ data \ is \ theoretically \ the \ same \ as \ I_D \ and \ I_{DM} \ , \ in \ real \ applications \ , \ should \ be \ limited \ by \ total \ power \ dissipation.$





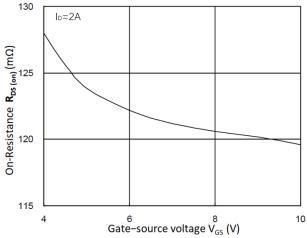


Figure 1. Output Characteristics

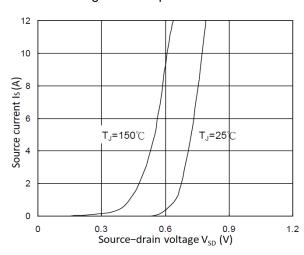


Figure 2. R<sub>DS</sub>(on) vs. V<sub>GS</sub>

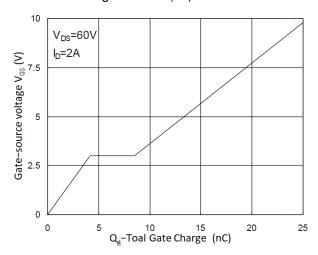


Figure 3. Forward Characteristics of Reverse

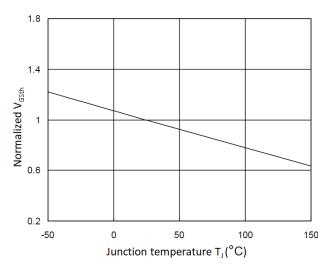


Figure 4. Gate Charge Character

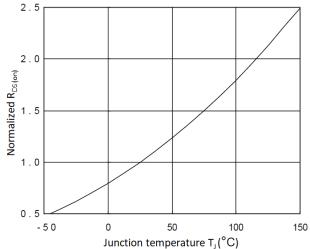


Figure 5. Normalized V<sub>GSth</sub> vs. T<sub>J</sub>

Figure 6. Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>

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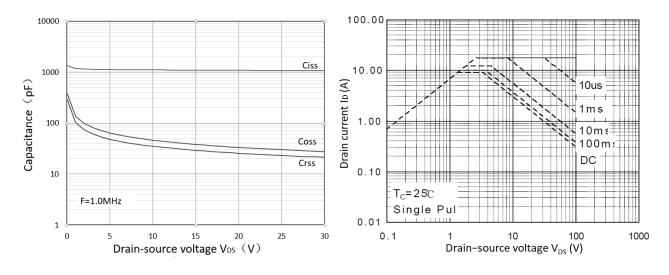


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

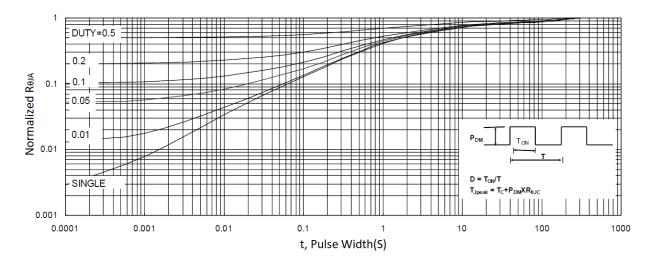


Figure 9. Normalized Maximum Transient Thermal Impedance

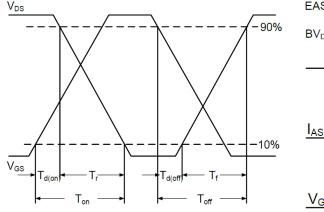


Figure 10. Switching Time Waveform

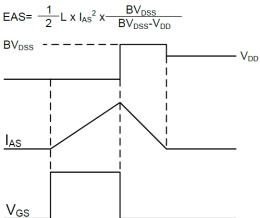
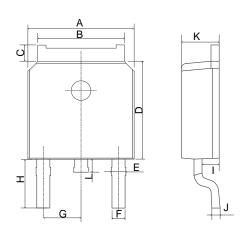


Figure 11. Unclamped Inductive Switching

Waveform



## **Mechanical Dimensions for TO-252**



# **COMMON DIMENSIONS**

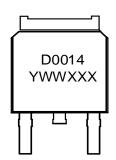
	MM			
SYMBOL	MIN	MAX		
А	6.40	6.80		
В	5.13	5.50		
С	0.88	1.28		
D	5.90	6.22		
Е	0.68	1.10		
F	0.68	0.91		
G	2.29REF			
Н	2.90REF			
I	0.85	1.17		
J	0.51REF			
K	2.10	2.50		
L	0.40	1.00		



## **Ordering Information**

Part	Package	Marking	Packing method
WMO09N10T1	TO-252	D0014	Tape and Reel

## **Marking Information**



D0014 = Device code

YWWXXX= Date code

# **Contact Information**

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